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## **PROCEEDINGS**

## Research on the Fabrication and Properties of Si<sub>3</sub>N<sub>4</sub> Ceramic Radomes via Vat Photopolymerization (VPP)

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## **ABSTRACT**

Silicon nitride ( $Si_3N_4$ ) ceramics with outstanding comprehensive properties, have become important candidate materials for components like radomes and antenna windows. In this study, the vat photopolymerization (VPP) technique was used to fabricate  $Si_3N_4$  ceramic radomes. Our research centered on optimizing the curing properties of ceramic slurries and precisely regulating the comprehensive properties of the ceramics. Several methods were proposed to modify the curing depth of  $Si_3N_4$  ceramic slurry, including thermosetting resin coating, sintering aid coating, oxidation coating, double coating, etc. Moreover, a pore-forming agent modification method was also proposed, which enabled the VPP printing of  $Si_3N_4$  ceramic parts with well-controlled pore structure. Subsequently, the correlations among process parameters, microstructure, and the properties of  $Si_3N_4$  ceramics were successfully established. This research intended to offer a valuable reference for the further research and application of  $Si_3N_4$  ceramics in the radome field.

## **KEYWORDS**

Vat photopolymerization (VPP); silicon nitride (Si<sub>3</sub>N<sub>4</sub>); coating modification; ceramic radomes

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